

# Chun Zhang

## List of Publications by Citations

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29  
papers

352  
citations

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g-index

29  
ext. papers

434  
ext. citations

4.2  
avg, IF

3.56  
L-index

#	Paper	IF	Citations
29	Effects of dual-layer coatings on microstructure and thermal conductivity of diamond/Cu composites prepared by vacuum hot pressing. <i>Surface and Coatings Technology</i> , <b>2015</b> , 277, 299-307	4.4	61
28	Preparation of AlBi alloys by a rapid solidification and powder metallurgy route. <i>Materials and Design</i> , <b>2015</b> , 87, 996-1002	8.1	53
27	Effect of bimodal microstructure on the tensile properties of selective laser melt Al-Mg-Sc-Zr alloy. <i>Journal of Alloys and Compounds</i> , <b>2020</b> , 815, 152422	5.7	29
26	Microstructure and thermal properties of Al/W-coated diamond composites prepared by powder metallurgy. <i>Materials and Design</i> , <b>2016</b> , 95, 39-47	8.1	28
25	Low-temperature densification of diamond/Cu composite prepared from dual-layer coated diamond particles. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2015</b> , 26, 185-190	2.1	20
24	Effects of annealing on microstructure and mechanical properties of rapidly solidified Cu-3 wt% Ag-1 wt% Zr. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , <b>2019</b> , 739, 357-366	5.3	17
23	Microstructure and properties of Al/Sip composites for thermal management applications. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2015</b> , 26, 4234-4240	2.1	16
22	Microstructure and thermal behavior of diamond/Cu composites: Effects of surface modification. <i>Diamond and Related Materials</i> , <b>2018</b> , 86, 98-108	3.5	16
21	Effect of copper content on microstructure and mechanical properties of Al/Sip composites consolidated by liquid phase hot pressing. <i>Materials and Design</i> , <b>2016</b> , 110, 10-17	8.1	14
20	Effect of solidification rate on the coarsening behavior of precipitate in rapidly solidified Al-Si alloy. <i>Progress in Natural Science: Materials International</i> , <b>2016</b> , 26, 391-397	3.6	12
19	Effects of Mn and Sn on microstructure of Al <sub>70</sub> Si <sub>10</sub> Mg alloy modified by Sr and Al <sub>3</sub> TiB. <i>Transactions of Nonferrous Metals Society of China</i> , <b>2015</b> , 25, 3546-3552	3.3	11
18	Influence of hot isostatic pressing and forging on the microstructure and mechanical properties of Cu-3Ag-1Zr alloys. <i>Materials and Design</i> , <b>2019</b> , 168, 107676	8.1	10
17	Microstructure, mechanical and thermo-physical properties of Al <sub>70</sub> Si <sub>10</sub> Mg alloys. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , <b>2018</b> , 730, 57-65	5.3	10
16	Thermal cycling reliability of Al/50Sip composite for thermal management in electronic packaging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2015</b> , 26, 4894-4901	2.1	9
15	Effect of Particle Size on Microstructure and Cold Compaction of Gas-Atomized Hypereutectic Al-Si Alloy Powder. <i>Metallurgical and Materials Transactions B: Process Metallurgy and Materials Processing Science</i> , <b>2015</b> , 46, 824-830	2.5	9
14	Influence of titanium coating on the microstructure and thermal behavior of Dia./Cu composites. <i>Diamond and Related Materials</i> , <b>2019</b> , 97, 107449	3.5	7
13	Microstructures and elevated temperature properties of rapidly solidified Cu-3Ag-0.5Zr and Cu-3Ag-0.5Zr-0.4Cr-0.35Nb alloys. <i>Journal of Alloys and Compounds</i> , <b>2019</b> , 803, 1037-1044	5.7	6

12	Polynomial regression and interpolation of thermodynamic data in AlSiMgFe system. <i>Calphad: Computer Coupling of Phase Diagrams and Thermochemistry</i> , <b>2015</b> , 48, 175-183	1.9	6
11	Enhancing densification capacity and properties of Al/diamond composites by partial liquid hot pressing. <i>Surface and Coatings Technology</i> , <b>2017</b> , 313, 347-354	4.4	5
10	Effect of minor scandium addition on the microstructure and properties of Al <sub>3</sub> Si alloys for electronic packaging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2019</b> , 30, 20770-20777	2.1	4
9	Inhibited cold compactibility of rapidly solidified AlSi alloy powder with large solidification rate. <i>Advanced Powder Technology</i> , <b>2015</b> , 26, 1458-1464	4.6	3
8	Ultrafine grained Cu <sub>3</sub> Ag-xZr (x = 0.5, 1.0 wt%) alloys with high strength and good ductility fabricated through rapid solidification and cryorolling. <i>Materials Science &amp; Engineering A: Structural Materials: Properties, Microstructure and Processing</i> , <b>2020</b> , 778, 139095	5.3	3
7	Microstructure stability and tensile properties of Cu-3Ag-1Zr alloy fabricated by rapid solidification and cold rolling. <i>Materials Characterization</i> , <b>2020</b> , 160, 110091	3.9	3
6	Study on Novel Heterogeneous Packaging Material and Housing Design for Spaceborne T/R Module. <i>IOP Conference Series: Materials Science and Engineering</i> , <b>2019</b> , 677, 022092	0.4	0
5	Achieving high strength and high conductivity synergy through hierarchical precipitation stimulated structural heterogeneities in a Cu-Ag-Zr alloy. <i>Materials and Design</i> , <b>2022</b> , 110777	8.1	0
4	Low-temperature annealing behavior and tensile properties of the rapidly solidified Cu <sub>3</sub> Ag <sub>0.5</sub> Zr <sub>0.4</sub> Cr <sub>0.35</sub> Nb alloy reinforced by cold rolling. <i>Journal of Alloys and Compounds</i> , <b>2020</b> , 828, 154371	5.7	
3	Microstructure, properties, and corrosion resistance of as-cast Al-12Si-1.0Mn-0.6 Mg-xSc alloys. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2021</b> , 32, 13279-13290	2.1	
2	Precipitation behavior and properties of Al <sub>3</sub> Si <sub>0.5</sub> X (X = Sc, La, Nb) alloys. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2022</b> , 33, 7380-7395	2.1	
1	Microstructure and properties of Al-Si/Al-SiCp bilayer composite for electronic packaging. <i>Journal of Materials Science: Materials in Electronics</i> , <b>2022</b> , 33, 7811-7823	2.1	